

## REMARKS

### Claim Objections

The Examiner indicated that claim 25 contains a minor typographical error. Claim 25 has been amended.

### 35 U.S.C. § 103 Rejections

The Examiner has rejected claims 1, 3-4, 6-18, 20-22, 25, and 26 under 35 U.S.C. § 103(a) as being unpatentable over Jiang, et al. in view of Chia, et al., and further in view of Bellaar, et al., and further in view of Hoffmeyer. This includes independent claims 1, 18, 22, and 25. Applicant submits that these claims are patentable over the cited references.

As noted by the Examiner, Jiang and Chia fail to disclose the capacitor contact prevention structure. The Examiner contends that Bellaar discloses the capacitor contact prevention structure. Applicant submits, with respect, that Bellaar does not disclose the capacitor contact prevention structure. It appears that the Examiner has relied on Hoffmeyer merely because of certain temperatures that are disclosed in Hoffmeyer.

Bellaar in Figure 3 discloses resilient contacts 105 on top of composite socket terminals 106. Column 10, lines 54-56, state as follows:

*"Other microelectronic elements, such as resistors, capacitors, inductors, etc., may also be connected to the test socket assembly."*

Column 10, line 65 to column 11, line 1, further state as follows:

*“The element is plugged into the test socket assembly such that one or more of the solder balls of the element engages the resilient contacts of the test socket assembly.”*

The capacitor can thus be attached to the resilient contacts 105. There is, however, no suggestion that the capacitor can be attached to the bottom of the resilient contacts 105, i.e., between the composite socket terminals 106. Bellaar specifically states that such a capacitor should be removable. Column 10, lines 59-64, state as follows:

*The microelectronic element may be temporarily plugged into the test socket assembly in order to test the microelectronic element. If the element is working properly, then the microelectronic element can be permanently incorporated into the test socket assembly to form a microelectronic device.*

Column 11, lines 2-5 further state as follows:

*“The element may then be removed and later incorporated into a separate microelectronic device or the element may be permanently attached to the test socket assembly to form a microelectronic device.”*

How can the capacitor be located between the composite socket terminals 106 and still be removed? Clearly, the larger upper surfaces of the resilient contacts 105 are for capacitors or other devices to be mounted thereto.

There is thus no suggestion that a capacitor can be located between the composite socket terminals 106. Hence, there is no suggestion that the composite socket terminals 106 can be used to prevent the capacitor from coming into contact with the rigid interposer 110. Neither has the Examiner cited any art that suggests this capacitor contact prevention structure.

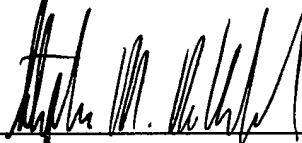
Applicant, accordingly, respectfully requests withdrawal of the rejections of claims 1, 3-4, 6-18, 20-22, 25, and 26, and an allowance of the patent application.

If the Examiner believes a telephone conference would expedite or assist in the allowance of the present application, the Examiner is invited to call Stephen M. De Klerk at (408) 720-8300.

Please charge any shortages and credit any overages to Deposit Account No. 02-2666. Any necessary extension of time for response not already requested is hereby requested. Please charge any corresponding fee to Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP



Date: April 12, 2005

Stephen M. De Klerk  
Reg. No. 46,503

12400 Wilshire Boulevard  
Seventh Floor  
Los Angeles, California 90025-1026  
(408) 720-8300